



arm



Leveraging Arm Architecture and Rescale Cloud HPC Platform for Enhanced OpenFOAM Performance: A Comparative Analysis

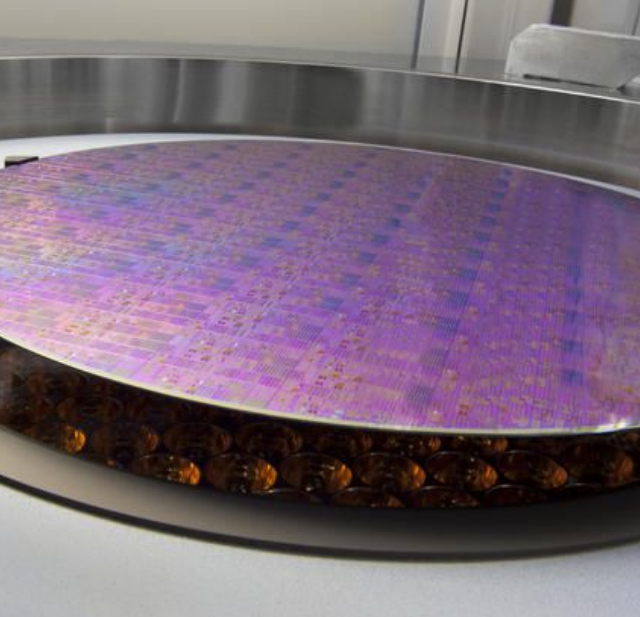
CCFR Webinar
23 January 2024

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Agenda

- ❖ Rescale Introduction
- ❖ Arm Partnership
- ❖ Chip Architecture
- ❖ Single Node Benchmarks
- ❖ Multi Node Benchmarks
- ❖ External Solver - Michelin's Requirements
- ❖ How can you enable your code on `aarch64`?
- ❖ Conclusions



Rescale Completes the Digital Thread in a Diverse Ecosystem

OpenFOAM OpenFOAM
The OpenFOAM Foundation



Application / ISV Publishing
(Commercial, Open-source, Custom)



PLM, SPDM,
Workflow
Orchestration,
Schedulers



NFS / DL /
DW
Connectors



Hyperscaler CSPs, SCSP / On-Prem
Technology Connectors



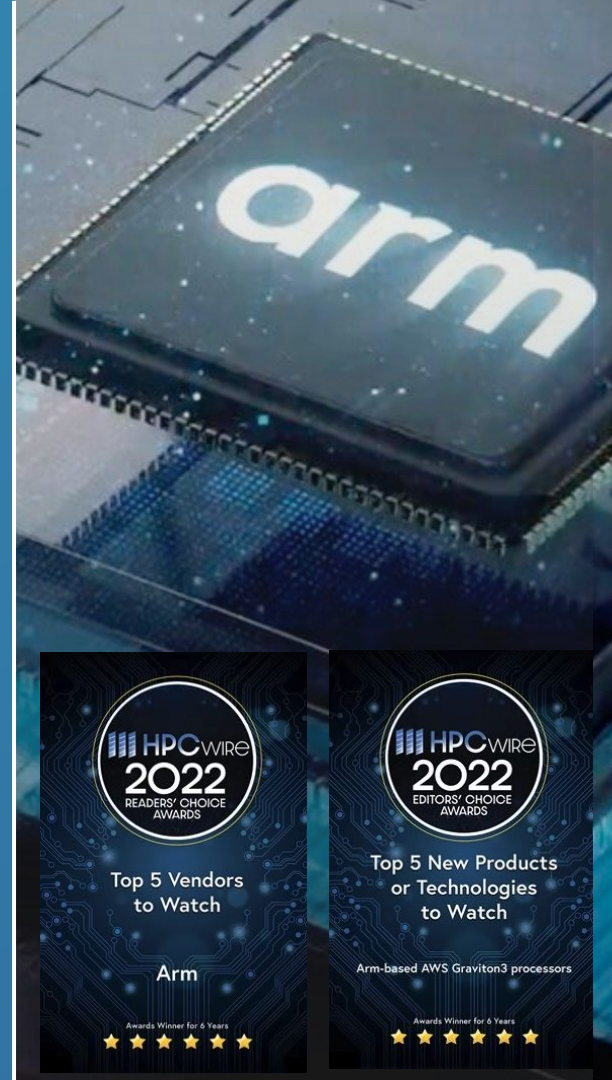


Rescale Customer Spotlight

Company: Arm
Industry: Engineering Consulting
Use Cases: Chip Design, Design Verification, High Throughput Computing

“Rescale is helping Arm usher in a new era for chip design. Arm-powered cloud computing combined with the intelligent automation of the Rescale platform brings many benefits to our design and verification processes by not only helping Arm engineers create the world’s most advanced IP, but also enabling our ecosystem to take full advantage of multi-cloud resources for accelerating R&D. With Rescale, our engineering teams can access the best computing resources they need – including the price/performance and sustainability benefits of running on Arm architecture – whenever they need them.”

— Mark Galbraith, VP of Productivity Engineering



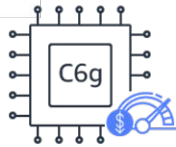
AWS Graviton3

Hardware based on Arm technologies

Graviton2 Processor



Frequency
2.5 GHz



Many core
architecture
64 cores



Peak Flops
1280 Gflops
2x128-bit NEON

Non-NUMA



Peak Memory B/W
204 GB/s
8 channels of DDR4

7 nm

Arm Neoverse N1

Greener Compute 60% less energy*



Graviton3 Processor



Frequency
2.6 GHz



Many core
architecture
64 cores



Peak Flops
2662 Gflops
2x256-bit SVE
or 4x128-bit NEON

Non-NUMA



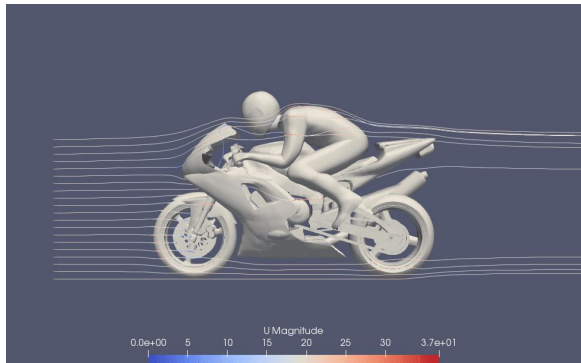
Peak Memory B/W
307 GB/s
8 channels for DDR5

Energy
efficiency
5 nm

Arm Neoverse V1

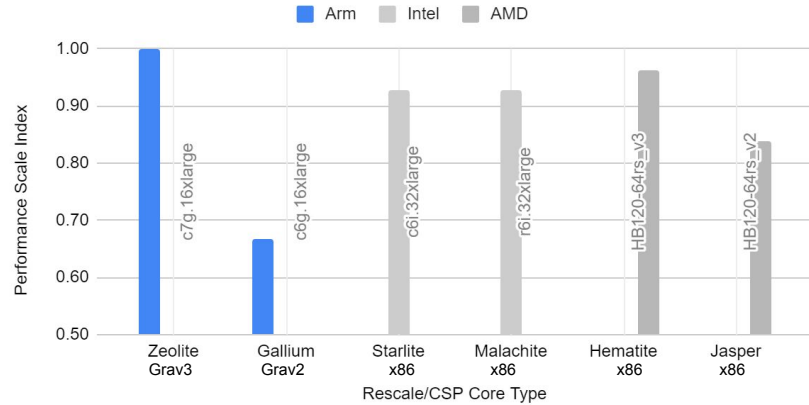
Single Node Benchmarks

- MotorBike Tutorial simpleFoam
- OpenFOAM+ v2212
- 0.35 million cells
- 64 cores per node
- aarch64 and x86_64 compiled with gcc



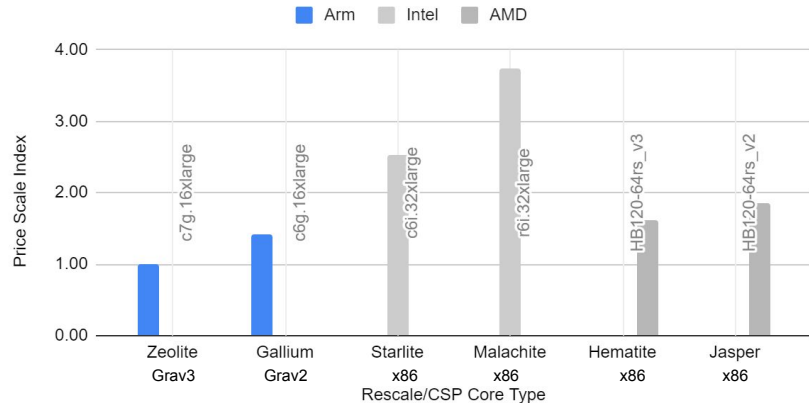
Performance Scale Index

Higher is better



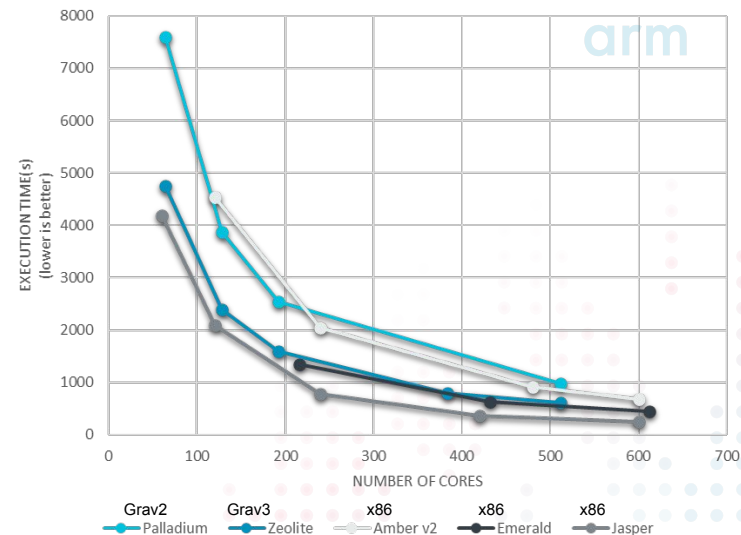
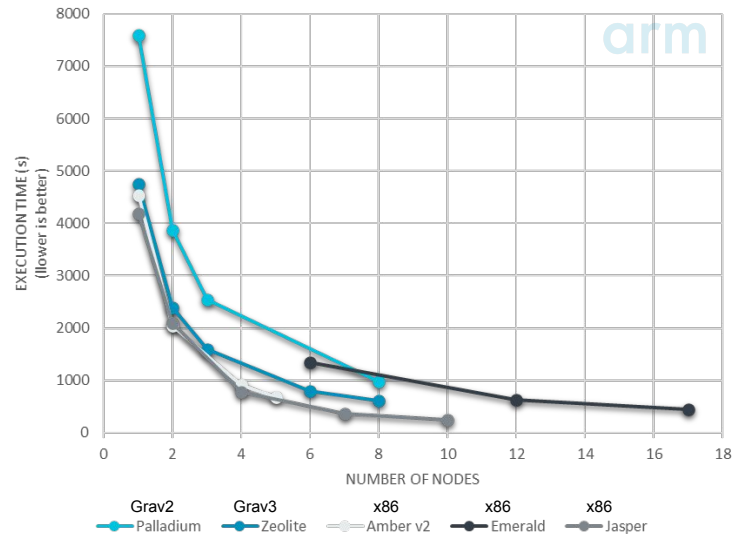
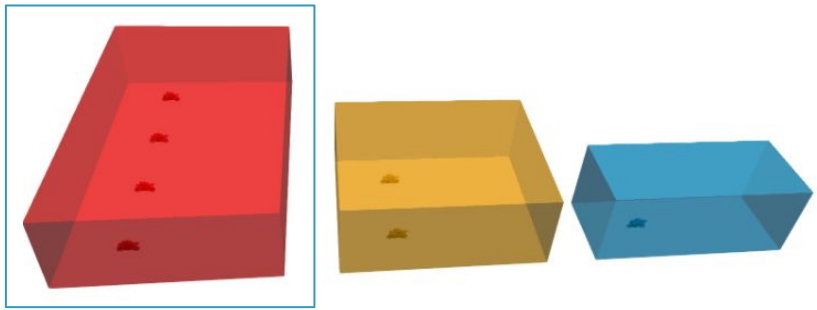
Price Scale Index (CSP List Price)

Lower is better



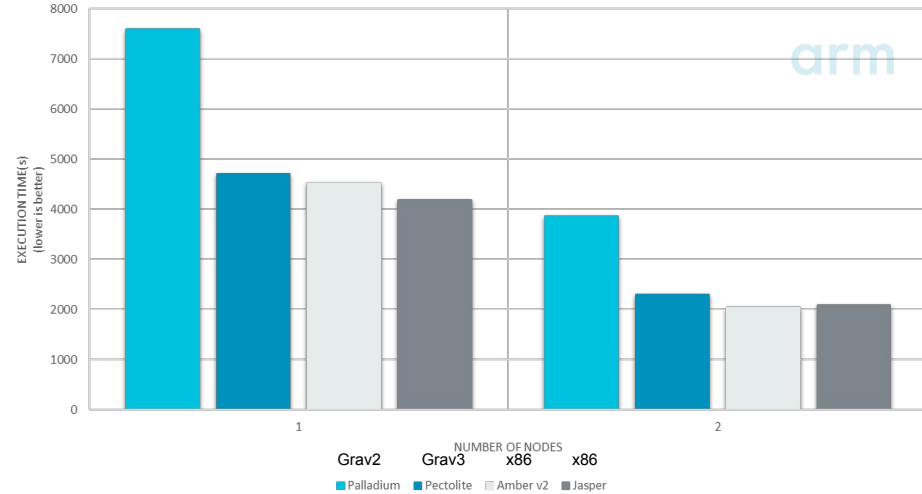
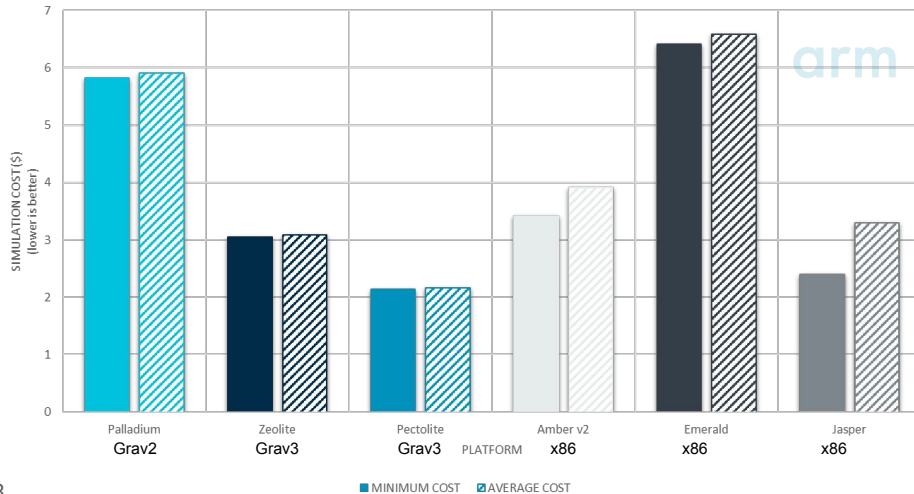
Multi Node Benchmarks

- HPC MotorBike simpleFoam LARGE
 - [High Performance Computing Technical Committee](#)
- OpenFOAM+ v1912
- 34 million cells
- OpenMPI
- aarch64 and x86_64 compiled with gcc



Cost Performance

- For a given number of nodes this OpenFOAM test case runs slightly faster on AMD based instances, up to 13%.
- The main reason is the memory bandwidth at the node level : 350 GB/s for both Amber v2 and Jasper versus 307 GB/S for Pectolite and 204GB/s for Palladium

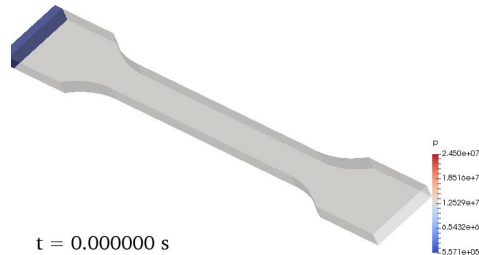


- Pectolite, AWS Graviton 3 based on Arm Neoverse V1 technologies minimizes the cost of simulation.
- Differences between AVERAGE COST and MINIMUM COST on Amber v2 and Jasper could be due to the fact that the test case starts to fit into L3 cache for a higher number of nodes

External Solver - Michelin's Requirements

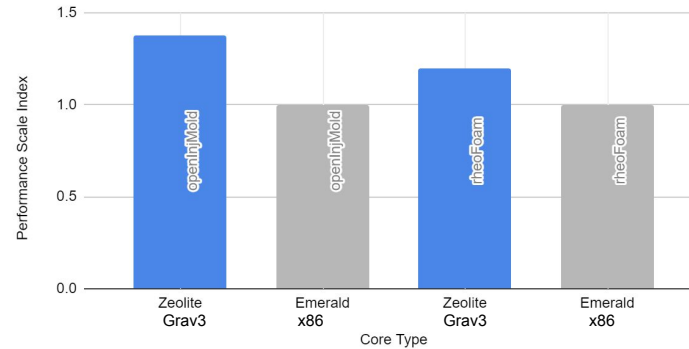


- Michelin is working together with the University of Minho on their material science simulation R&D workflow
- Injection molding and extrusion models in OpenFoam are used to investigate material production characteristics
- External OF solver used [OpenInjMod](#) and [RheoTool](#) (OpenFOAM 7)
- Compiled for `aarch64` and `x86_64` with `gcc`
- Pre-compiled library implementation



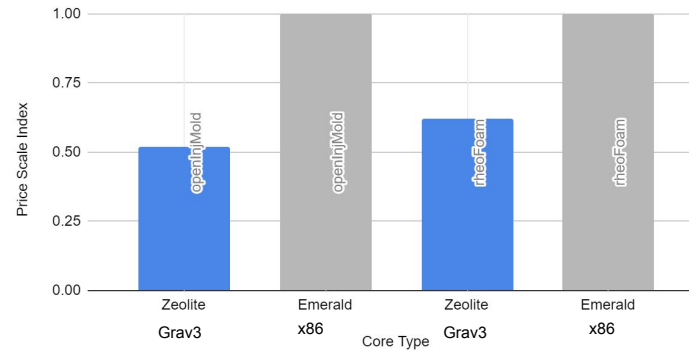
Performance Scale Index

Higher is better



Price Scale Index (CSP List Price)

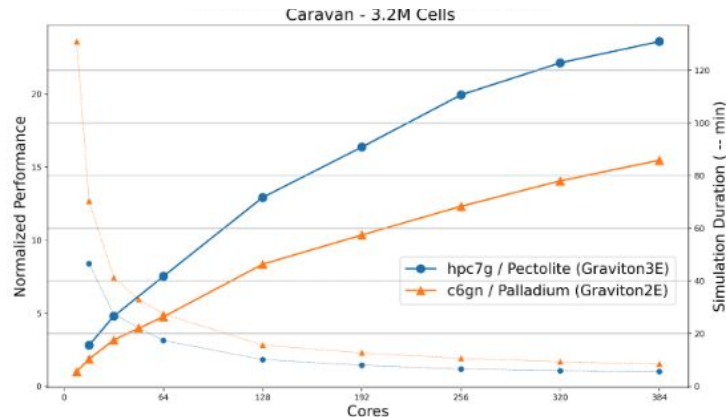
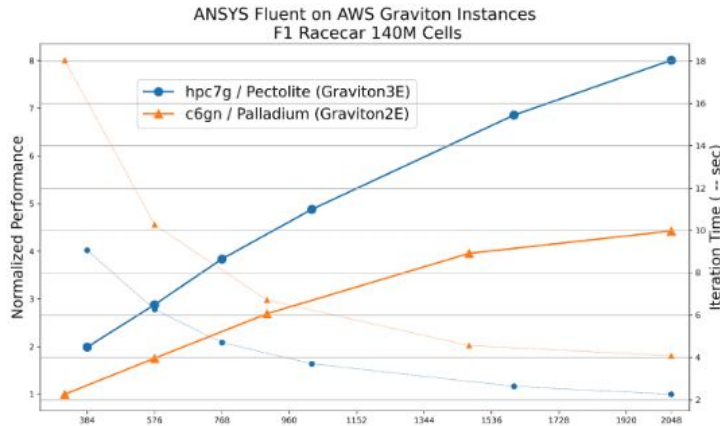
Lower is better



Leveraging aarch64 on Rescale

- Various ways of deploying aarch64 software:
- Most major simulations software already available:
 - Siemens CCM+, ANSYS Fluent, LS-Dyna, LAMMPS, GROMACS, SU2, Nvidia NGC Catalog
- Deploy your own containerised software
 - Docker, Aptainer, Singularity
- Compile your full stack on a aarch64 instance:
 - gcc compilers available
 - armcc and Arm Performance Libraries
 - armclang|armclang++ (Arm C/C++ Compiler)
- Publish your aarch64 software on the platform using [Rescale Software Publisher](#)

<https://rescale.com/blog/rescale-automates-the-deployment-of-ansys-ls-dyna-and-a-nsys-fluent-workloads-on-amazon-ec2-hpc7g-instances/>



arm
COMPILER



Conclusions

- ❖ The Rescale Arm partnership allows engineers to **seamlessly leverage** the latest CPU technologies to drive their digital product development cycle
- ❖ AWS Graviton 3 is a major step forward in terms of HPC **applicability and performance** compared to its predecessor.
- ❖ Single node benchmarks show that the latest Arm architecture chips are **industry leading** in both Performance and Cost
- ❖ Multi node benchmarks show that Arm chips are on a par with AMD and Intel's industry standard cloud HPC core types performance wise, whilst **leading the pack** when it comes to cost
- ❖ Engineers are able to develop and run their own OpenFoam solvers on Rescale and deploy them on the architecture of their choice with a consistent methodology in **matter of days**
- ❖ Migrating to Arm is a **trivial exercise** for **all compatible HPC workflows** on Rescale

Acknowledgements

➤ Arm

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➤ Michelin

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➤ Rescale

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- Guillaume Trainar - Senior Account Executive
- David Green - Account Executive
- Scott Wieland - HPC Engineer
- Jared Workman - Manager, HPC Engineering



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DEMO

```
[uprod_gkUxGc@ip-10-56-10-166 ~/work/shared]$
```